SK-AM62B-P1 Design Package Content Overview



Table 1 lists names of the folders and file names in the folders along with the format for all the files that have been included in the SK-AM62B-P1. SK-AM62B-P1 Starter Kit Evaluation Module (SKEVM), a low cost SKEVM built around the AM623/AM625 SoC, (13mm x 13mm, 0.5mm pitch, 425-pin FCCSP BGA [ALW]). The processor comprises of a Quad-Core 64-bit Arm® Cortex® A53 microprocessor, Single-core Arm Cortex-R5F MCU and an Arm Cortex-M4F MCU. The product overview document is available on the SK-AM62B-P1 product folder on TI.com for customers to review before downloading the single Zip folder.

Table 1. Proc142A

FOLDER (1st level)	FOLDER (2nd level)	Files Inside	File type
		Proc142A_Folders_Files_List	XLS
1_SCHEMATIC	PDF	PROC142A(002)_SCH_With_Design_UpdatesNotes_V1.0	PDF
	PDF -Backup_SK_Schematic	PROC142A(002)_sch	PDF
		Schematic_Revision_Readme	PDF
	ORCAD	PROC142A(002)_Sch_With_Design_UpdatesNotes_V1.0	DSN
	ORCAD - Backup_SK_Schematic	PROC142A_SCH	DSN
2_BOM		PROC142A(002)_BOM_With_Design_UpdatesNotes_V1.0	XLS
	Backup_SK_Schematic_BOM	PROC142A(002)_BOM	XLS
3_Board_File	Allegro	PROC142A_BRD	BRD
	Simulation Scorecard	AM62x_Simulation_Scorecard	PDF
	Altium_ASCII	PROC142A_BRD	ALG
4_Gerber	ODBGBR	PROC142A_ODBGBR	ZIP
	274X	PROC142A_274xGBR	ZIP
	IPC-D-356_NETLIST	PROC142A_BRD	IPC
5_Gerber_PDF	FAB	PROC142A_FAB	PDF
	PCB LAYERS	PROC142A-LAYERS	PDF
	Geber Layers	PROC142A-LAYERS	PDF
6_Assembly_Models_P ackage	2D	PROC142A_BASY	DXF
		PROC142A_TASY	DXF
	3D	PROC142A_3D_STEP	STP
	IDF	PROC142A_BRD	EMP
		PROC142A_BRD	EMN
	Assembly_Drawing_PDF	PROC142A_ASSEMBLY	PDF
		PROC142A_TASY	PDF
		PROC142A_BASY	PDF
	STNL	art_aper + 8 x .ART files	ART
	XY-REP	PROC142A_XY-REP	XLS
7_PCB_LAYER_STACK UP		SK-AM62B-P1_Proc142A_Layer_STACKUP	PDF
8_Power_Supply_Sequ encing		SK-AM62B-P1_Proc142A_Power Sequence	PDF

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References

Texas Instruments, [FAQ] AM625 / AM623 Custom board hardware design - Design and Review Notes for Reuse of SK-AM62B-P1 Schematics

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